

# MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

## MJD42CT4G(MS)

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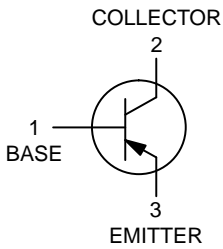

Product specification

**TRANSISTOR (PNP)**

**FEATURES**

- Designed for General Purpose Amplifier and Low Speed Switching Applications.
- Lead Formed for Surface Mount Applications in Plastic Sleeves
- Electrically Similar to Popular TIP41 and TIP42 Series
- Monolithic Construction With Built-in Base-Emitter Resistors

**Reference News**

PACKAGE OUTLINE	COMPLEMENTARY	Marking
 <p>1.BASE 2.COLLECTOR 3.EMITTER</p>		

Notes :XXX represents the order code.

**MAXIMUM RATINGS (Ta=25 °C unless otherwise noted)**

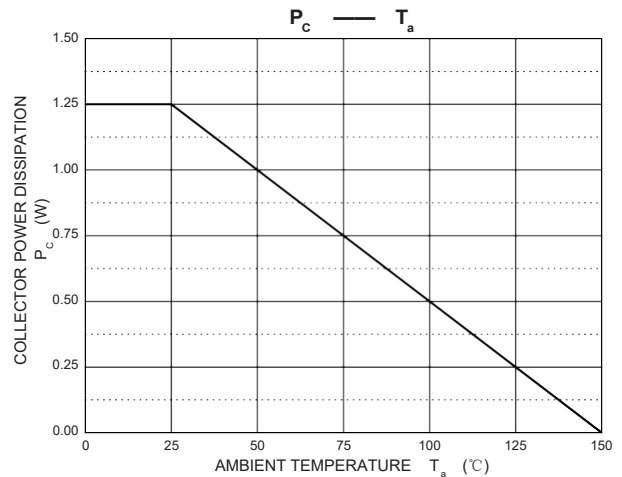
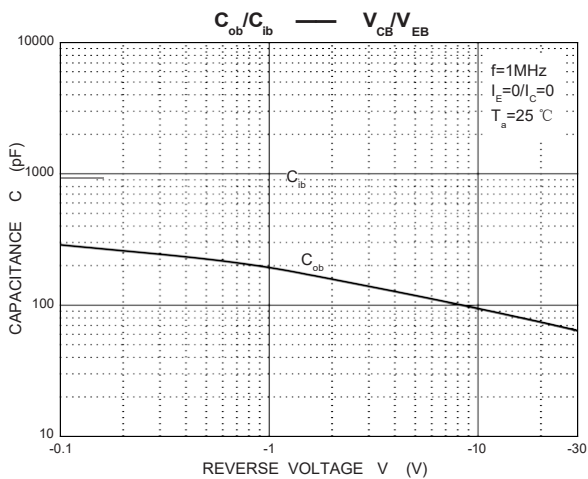
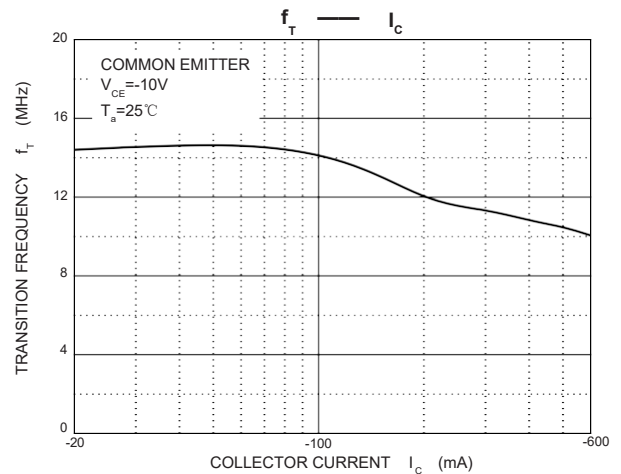
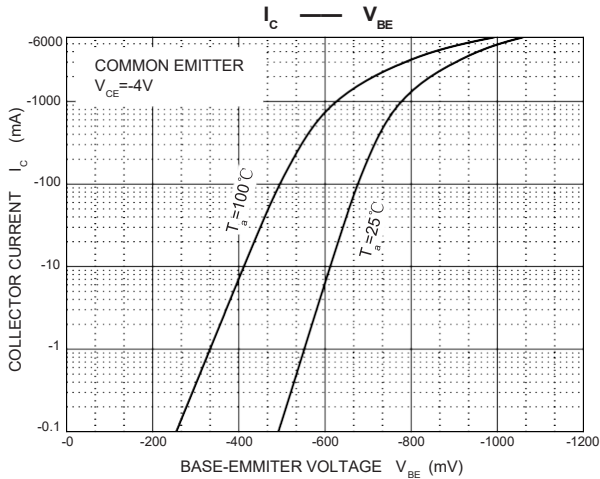
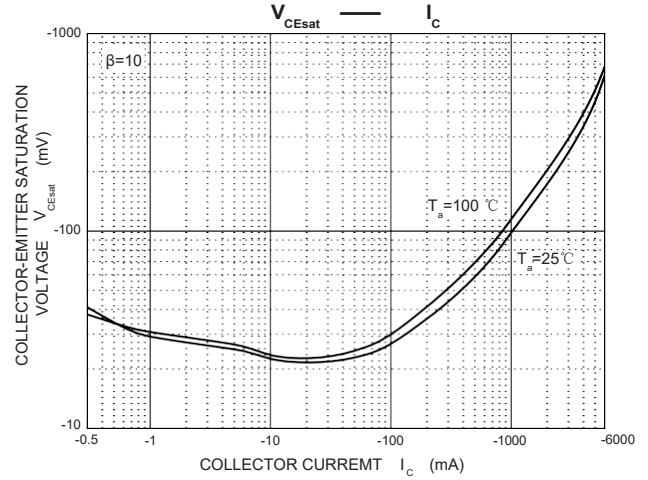
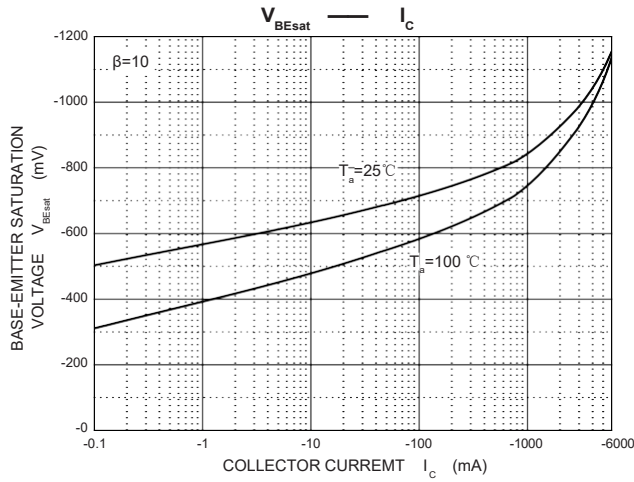
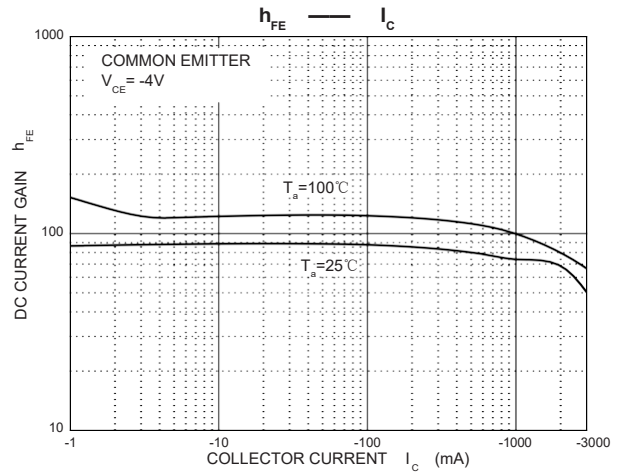
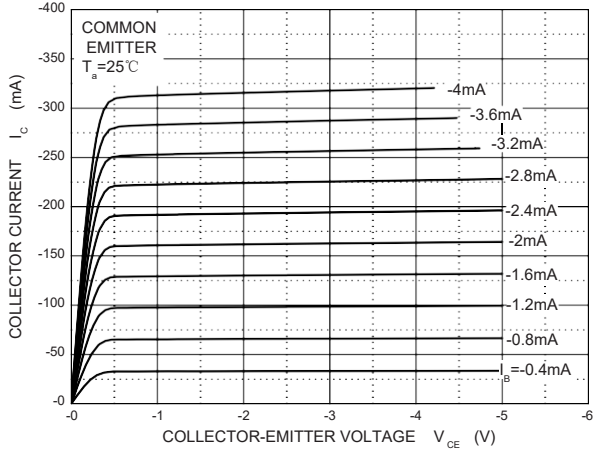
Symbol	Parameter	Value	Unit
V <sub>CB0</sub>	Collector-Base Voltage	-100	V
V <sub>CEO</sub>	Collector-Emitter Voltage	-100	V
V <sub>EBO</sub>	Emitter-Base Voltage	-5	V
I <sub>C</sub>	Collector Current -Continuous	-6	A
I <sub>CP</sub> *	Collector Current -Pluse	-10	A
P <sub>C</sub>	Collector Power Dissipation	1.25	W
T <sub>J</sub> , T <sub>stg</sub>	Operating Junction and Storage Temperature Range	-55-150	°C

**ELECTRICAL CHARACTERISTICS (T<sub>a</sub>=25 °C unless otherwise specified)**

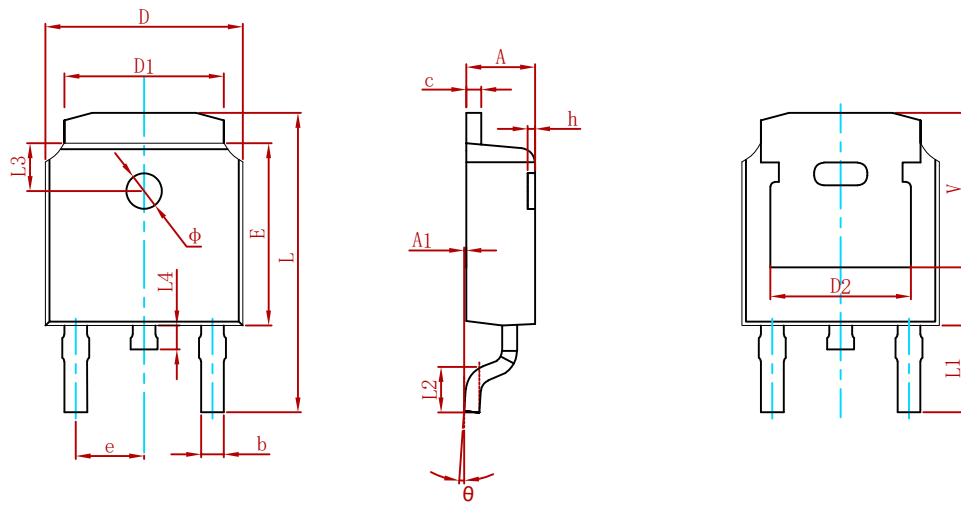
Parameter	Symbol	Test conditions	Min	Typ	Max	Unit
Collector-base breakdown voltage	V <sub>(BR)CBO</sub>	I <sub>C</sub> =-100μA, I <sub>E</sub> =0	-100			V
Collector-emitter breakdown voltage	V <sub>CEO(sus)</sub>	I <sub>C</sub> =-30mA, I <sub>B</sub> =0	-100			V
Emitter-base breakdown voltage	V <sub>(BR)EBO</sub>	I <sub>E</sub> =-100μA, I <sub>C</sub> =0	-5			V
Collector cut-off current	I <sub>CEO</sub>	V <sub>CB</sub> =-60V, I <sub>E</sub> =0			-50	μA
Emitter cut-off current	I <sub>EBO</sub>	V <sub>EB</sub> =-5V, I <sub>C</sub> =0			-0.5	mA
DC current gain	h <sub>FE(1)</sub>	V <sub>CE</sub> =-4V, I <sub>C</sub> =-0.3A	30			
	h <sub>FE(2)</sub>	V <sub>CE</sub> =-4V, I <sub>C</sub> =-3A	15		75	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	I <sub>C</sub> =-6A, I <sub>B</sub> =-0.6A			-1.5	V
Base-emitter voltage	V <sub>BE</sub>	V <sub>CE</sub> =-4V, I <sub>C</sub> =-6A			-2	V
Transition frequency	f <sub>T</sub>	V <sub>CE</sub> =-10V, I <sub>C</sub> =-500mA, f=1MHz	3			MHz

\* Pulse Test: PW≤300μs, Duty Cycle≤2%

**Static Characteristic**

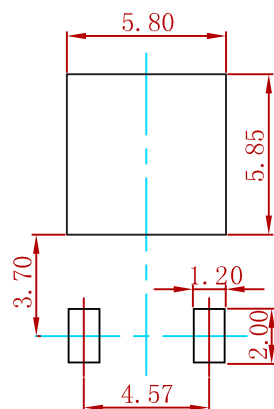


**PACKAGE MECHANICAL DATA**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
Φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

**Suggested Pad Layout**



- Note:
1. Controlling dimension: in millimeters.
  2. General tolerance: ± 0.05mm.
  3. The pad layout is for reference purposes only.

**REEL SPECIFICATION**

P/N	PKG	QTY
MJD42CT4G(MS)	TO-252	2500

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